

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)						
PCN #: TP Product Affected: Date Effective:	P1910-03 Date: November 18, 2019 Please refer to Page 2 for affected part numbers February 18, 2020	MEANS OF DISTINGUISHING CHANGED DEVICES: □ Product Mark □ Back Mark ■ Date Code Please refer to Page 2 for Date Code □ Other				
Contact:	Yimu Guo					
E-mail:	yimu.guo.yw@renesas.com	Samples: Available on request				
DESCRIPTION AND PURPOSE OF CHANGE: Die Technology Wafer Fabrication Process Assembly Process Equipment Material Testing Manufacturing Site Data Sheet Other - Die Revision Change This notification is to advise our customers of a top metal change to the select part numbers. Reason for Change: Under rare conditions, the listed devices may exhibit a no-output condition at power up in ZDB mode only. If the device and system have powered up normally, there are no issues with the devices; there are also no issues with devices operating in bypass mode. Description of Change: To avoid no-output condition, top metal design changes are made to the digital calibration circuits. This change also enables further ATE tests for these devices. Customers using the devices in one of the ZDB modes should let their IDT sales person know at the time of their order. The IDT Sales person will take the necessary steps to ensure the orders are tested with the updated device revision. There is no change to the orderable part number or datasheet specifications. The current version of this device will be discontinued as of the effective date on this notice. For further information please contact your local IDT sales and distribution channels.						
There is no chang		his device. There is no change to AC or DC performance of atch up and Characterization have been successfully completed.				
CUSTOMER AC	CKNOWLEDGMENT OF RECEIPT:					
		ange. Please E-Mail to grant approval or request additional ays of this notice it will be assumed that this change is acceptable.				

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PCN Type: Minor die revision change
Data Sheet Change: No datasheet change

Affected Part Numbers and Date Code Cutoff:

Affected Part Numbers	Date Code	
9ZML1232EKILF 9ZML1232EKILFT 9ZML1233EKILF		
9ZML1233EKILFT 9ZML1252EKILF	1940 and later	
9ZML1252EKILFT 9ZML1253EKILF 9ZML1253EKILFT		

Affected Part Numbers	Date Code
9ZXL1530DKILF 9ZXL1530DKILFT 9ZXL1550DKILF 9ZXL1550DKILFT 9ZXL1930DKILF 9ZXL1930DKILFT 9ZXL1950DKILFT 9ZXL1950DKILFF 9ZKL1950DKILFT 9Z61155DKILF 9Z61155DKILFT 9Z61195DKILFT 9Z61195DKILFT	1941 and later



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Qualification Information

Product Type: 9ZXL1950DKILF, 9ZML1233EKILF

Base Product AP711T Process Technology: CM018, 1P5M

Package Type: VFQFPN-72 Fab Location: TSMC 8B

Parts Covered: 9ZML1253EKILF, 9ZML1232EKILF, 9ZML1252EKILF, 9Z61195DKILF, 9ZXL1930DKILF,

9ZML1252EKILF, 9Z61195DKILF, 9ZXL1930DKILF, 9ZXL1550DKILF, 9Z61155DKILF, 9ZXL1530DKILF

Test Description	Conditions	Sample Size	Results (Rej/SS)	Comments
ESD: Human Body Model	JESD22-A114 (JS-001) Classification	5	Classification	Class 2 (2500V)
ESD: Charged Device Model	JESD22-C101 Classification	5	Classification	Class C3 (1000V)
Latch-Up	JESD78	6	0/6	Pass. Ta at 85°C
Electrical Characterization	Datasheet	5	Data reported in the datasheet	Complete